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Application Serial No. 08/845,897
Applicant(s): Imam et al.

PATENT APPLICATION
Docket No.: N.C. 77,897

impregnated with [solid bulk polymer] said polymeric matrix so as to completely penetrate said open cell structure of said foam and fill the cells thereof, said metal foam thickness no less than 3 times the average diameter of said cells.

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22. (amended) A method of forming a composite comprising the steps of: impregnating a metal foam, said metal foam having an open cell structure, with a resin component so as to completely penetrate said open cell structure of said foam and fill the open cells of said metal foam with said resin component; and

converting said resin component, within said cells, to a bulk solid, non-elastomeric polymerized resin, thus forming a composite comprising a matrix of said non-elastomeric polymerized resin, said matrix having therein said metal foam.

REMARKS

Claims 1 through 22 presently appear in this case. Claims 5, 6, 8 through 10, and 12 through 16 have been withdrawn from consideration as drawn to a nonelected invention. No claims have been allowed. The claims have been revised to define more clearly over Jarema et al. '401. Specifically, the claims now recite a metal/polymer composite having a polymeric matrix (page 12, line 1 of the specification as filed) with a open cell metal foam therein. The metal foam has been impregnated with the polymer so as to completely penetrate the open pore structure of the metal

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foam (page 8, lines 20 through 22 of the specification as filed) and fill the pores thereof (page 8, lines 9 through 14 of the specification as filed). Nothing in Jarema '401 discloses or suggests such a composite. Even Example 9 of Jarema '401 fails to teach or suggest the existence of a polymer matrix or the complete penetration of a resin or polymer into an open cell structure of a metal foam and filling of the cells thereof.

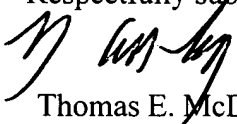
In conclusion, the present claims are submitted to fully comply with 35 U.S.C. §112 and to define patentable subject matter. Favorable reconsideration and allowance are earnestly solicited.

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